LucasMilhaupt
A Handy & Harman Company
Global Brazing Solutions

Technical Data Sheet

Solderite™ 50/50

NOMINAL COMPOSITION

Tin	50.0% ± 0.5%
Lead	50.0% ± 0.5%

PHYSICAL PROPERTIES

Color	White
Melting Point (Solidus)	361°F (183°C)
Flow Point (Liquidus)	414°F (212°C)
Specific Gravity	9.31
Density (Lbs /in^3)	0.34
Electrical Conductivity (%IACS)	10.9
Electrical Resistivity (Microhm-cm)	15.8

*IACS = International Annealed Copper Standard

SOLDERING CHARACTERISTICS

Solderite 50/50 is a general purpose solder used in applications involving soldering of copper and copper alloys and/or ferrous base alloys. This alloy offers satisfactory corrosion resistance properties.

This alloy should not be used in soldering of potable water systems due to its high lead content. A lead free alloy should be used instead. For water potable systems LM recommends Silver/Copper/Tin system such as Clean 'n Brite-No Lead, or Tin/Silver systems such as Clean 'n Brite and/or Clean 'n Brite 6.

PROPERTIES OF SOLDER JOINTS

The properties of a soldered joint are dependent upon numerous factors including base metal properties, joint design, metallurgical interaction between the base metal and the filler metal.

SPECIFICATIONS

Solderite 50/50 alloy conforms to the following specifications:

- American Society for Testing and Materials (ASTM) B32 Sn50

AVAILABLE FORMS

Wire, strip, engineered preforms, specialty preforms per customer specification, powder and paste.

WARRANTY CLAUSE

Lucas-Milhaupt, Inc. believes the information contained herein to be reliable. However, the technical information is given by Lucas-Milhaupt, Inc. without charge and the user shall employ such information at its own discretion and risk. Lucas-Milhaupt, Inc. assumes no responsibility for results obtained or damages incurred from the use of such information in whole or in part.

September 2008 Rev. 1